



FEATURES

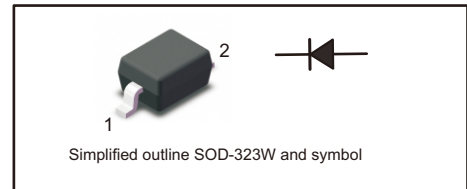
- For surface mounted applications
- Fast reverse recovery time
- Ideal for automated placement

MECHANICAL DATA

- Case: SOD-323W
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 5.48mg / 0.00019oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



MAXIMUM RATINGS (Ta = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	VRRM	100	V
Reverse voltage, total rms value	VR(RMS)	75	V
Forward current	IF	250	mA
Repetitive Peak Forward Current	IFRM	500.0	mA
Non-reptitive Peak Forward Surge Current	IFSM	at 1s	0.5
		at 1ms	1
		at 1us	4
Total Device Dissipation FR-5 Board, TA=25°C	PD	400	mW
Operating Temperature Range	TJ	-55~ +150	°C
Storage Temperature Range	Tstg	-55~ +150	°C

ELECTRICAL CHARACTERISTICS (TA = 25°C unless otherwise noted)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF=1mA			0.715	V
		IF=10mA			0.855	
		IF=50mA			1.00	
		IF=150mA			1.25	
Reverse Leakage Current	IR	V=VR=20V, TJ=25°C			0.03	uA
		V=VR=75V, TJ=25°C			1	
		V=VR=25V, TJ=150°C			30	
		V=VR=75V, TJ=150°C			50	
Junction Capacitance	Cj	VR=0V, f=1HMz		2		pF
Reverse recovery time (1)	trr				4	ns

Notes:

(1) Measured with IF=IR=10mA, Irr=0.1xIR, RL=100Ω



Typical Performance Characteristics

Fig.1 Power Derating Curve

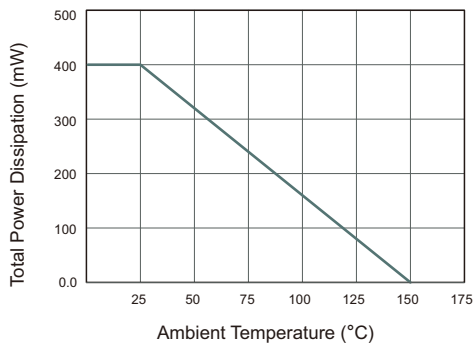


Fig.2 Typical Reverse Characteristics

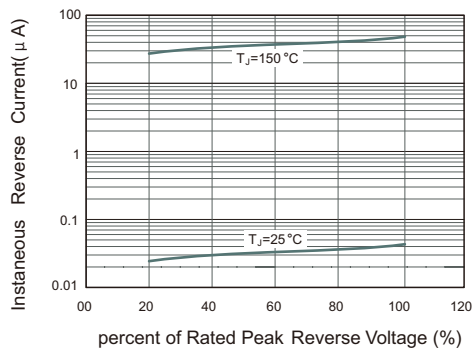


Fig.3 Typical Instaneous Forward Characteristics

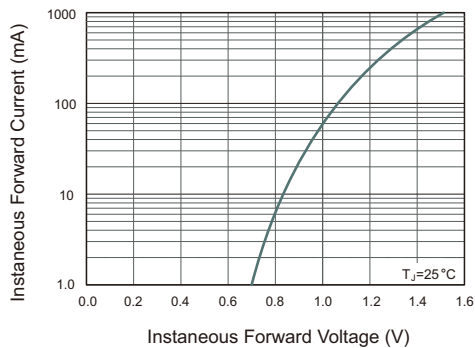
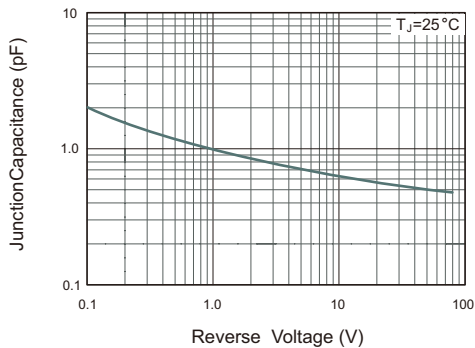


Fig.4 Typical Junction Capacitance

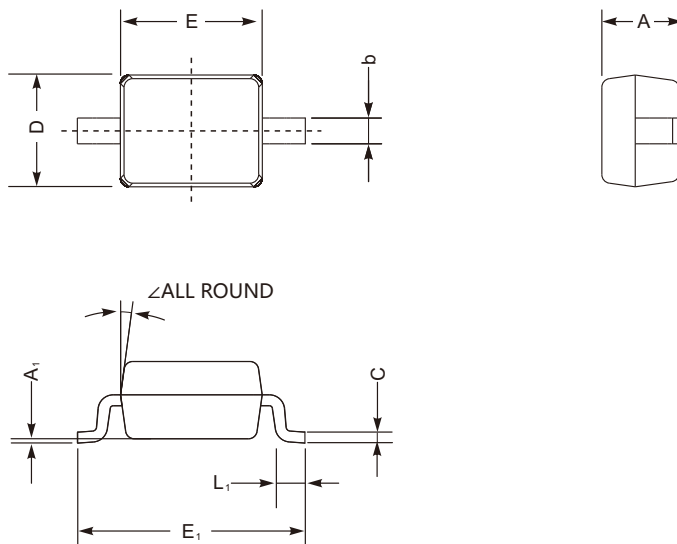




PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

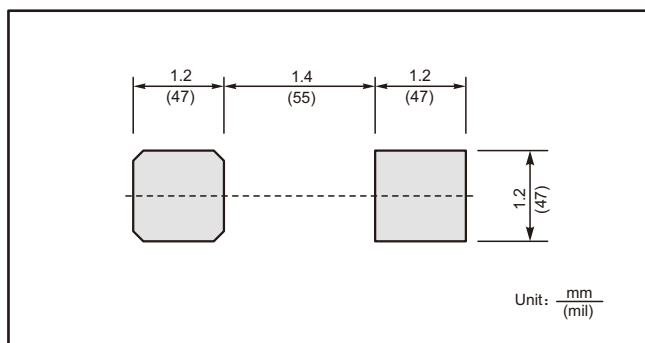
SOD-323W



SOD-323W mechanical data

UNIT		A	C	D	E	E ₁	b	L ₁	A ₁	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	55	100	9.8	7.9	—	

The recommended mounting pad size



Marking

Type number	Marking code
BAS316WB	A6



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